

# LatticeECP2/M sysIO Usage Guide

June 2013 Technical Note TN1102

#### Introduction

The LatticeECP2™ and LatticeECP2M™ sysIO™ buffers give the designer the ability to easily interface with other devices using advanced system I/O standards. This technical note describes the sysIO standards available and how they can be implemented using Lattice's ispLEVER® design software.

### sysIO Buffer Overview

LatticeECP2/M sysIO interface contains multiple Programmable I/O Cells (PIC) blocks. Each PIC contains two Programmable I/Os (PIO), PIOA and PIOB, connected to their respective sysIO Buffers. Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as "T" and "C").

Each Programmable I/O (PIO) includes a sysIO Buffer and I/O Logic (IOLOGIC). The LatticeECP2/M sysIO buffers supports a variety of single-ended and differential signaling standards. The sysIO buffer also supports the DQS strobe signal that is required for interfacing with the DDR memory. One of every 16/18 PIOs in the LatticeECP2/M contains a delay element to facilitate the generation of DQS signals. The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. For more information on the architecture of the sysIO buffer please refer to the LatticeECP2/M Family Data Sheet.

The IOLOGIC includes input, output and tristate registers that implement both single data rate (SDR) and double data rate (DDR) applications along with the necessary clock and data selection logic. Programmable delay lines and dedicated logic within the IOLOGIC are used to provide the required shift to incoming clock and data signals and the delay required by DQS inputs in DDR memory. The DDR implementation in the IOLOGIC and the DDR memory interface support are discussed in more detail in TN1105, <a href="LatticeECP2/M High-Speed I/O Interface">LatticeECP2/M High-Speed I/O Interface</a>.

# **Supported sysIO Standards**

The LatticeECP2/M sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into internally ratioed standard such as LVCMOS, LVTTL and PCI; and externally referenced standards such as HSTL and SSTL. The buffers support the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch). Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, RSDS, BLVDS, LVPECL, differential SSTL and differential HSTL. Tables 1 and 2 list the sysIO standards supported in LatticeECP2/M devices.

Table 9-1. Supported Input Standards

Input Standard	V <sub>REF</sub> (Nom.)	V <sub>CCIO</sub> ¹ (Nom.)			
Single Ended Interfaces					
LVTTL	_	_			
LVCMOS33	_	_			
LVCMOS25	_	_			
LVCMOS18	_	1.8			
LVCMOS15	_	1.5			
LVCMOS12	_	_			
PCI 33	_	3.3			
HSTL18 Class I, II	0.9	_			
HSTL15 Class I	0.75	_			
SSTL3 Class I, II	1.5	_			

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Table 9-1. Supported Input Standards (Continued)

Input Standard	V <sub>REF</sub> (Nom.)	V <sub>CCIO</sub> ¹ (Nom.)
SSTL2 Class I, II	1.25	_
SSTL18 Class I, II	0.9	_
GTL+ <sup>2</sup>	1.0	_
Differential Interfaces		
Differential SSTL18 Class I, II	<del>-</del>	_
Differential SSTL2 Class I, II	<del>-</del>	_
Differential SSTL3 Class I, II	<del>-</del>	_
Differential HSTL15 Class I	<del>-</del>	_
Differential HSTL18 Class I, II	<del>-</del>	_
LVDS, MLVDS, LVPECL, BLVDS, RSDS	<del>-</del>	_

<sup>1</sup> When not specified,  $V_{\text{CCIO}}$  can be set anywhere in the valid operating range.

Table 9-2. Supported Output Standards

Drive	V <sub>CCIO</sub> (Nom.)
4mA, 8mA, 12mA, 16mA, 20mA	3.3
4mA, 8mA, 12mA 16mA, 20mA	3.3
4mA, 8mA, 12mA, 16mA, 20mA	2.5
4mA, 8mA, 12mA, 16mA	1.8
4mA, 8mA	1.5
2mA, 6mA	1.2
4mA, 8mA, 12mA 16mA, 20mA	_
4mA, 8mA, 12mA 16mA, 20mA	_
4mA, 8mA, 12mA 16mA	_
4mA, 8mA	_
2mA, 6mA	_
N/A	3.3
8mA, 12mA	1.8
N/A	1.8
4mA, 8mA	1.5
N/A	3.3
8mA, 12mA	2.5
16mA, 20mA	2.5
N/A	1.8
8mA, 12mA	1.8
N/A	3.3
8mA, 12mA	2.5
16mA, 20mA	2.5
N/A	1.8
8mA, 12mA	1.8
8mA, 12mA	1.8
	4mA, 8mA, 12mA, 16mA, 20mA 4mA, 8mA, 12mA 16mA, 20mA 4mA, 8mA, 12mA, 16mA, 20mA 4mA, 8mA, 12mA, 16mA 4mA, 8mA 2mA, 6mA 4mA, 8mA, 12mA 16mA, 20mA 4mA, 8mA, 12mA 16mA, 20mA 4mA, 8mA, 12mA 16mA 4mA, 8mA 2mA, 6mA AmA, 8mA 2mA, 6mA N/A 8mA, 12mA N/A 8mA, 12mA 16mA, 20mA N/A 8mA, 12mA

<sup>2.</sup> GTL+ inputs can be supported using HSTL15 Class I inputs with VREF set to 1.0V and external VTT termination to 1.5V. Please see "sysIO Buffer Configurations" on page 6 for implementation details.



#### Table 9-2. Supported Output Standards (Continued)

Output Standard	Drive	V <sub>CCIO</sub> (Nom.)
Differential HSTL18, Class II	N/A	1.8
Differential HSTL15, Class I	4mA, 8mA	1.5
LVDS	N/A	2.5
MLVDS <sup>1</sup>	N/A	2.5
BLVDS <sup>1</sup>	N/A	2.5
LVPECL <sup>1</sup>	N/A	3.3
RSDS <sup>1</sup>	N/A	2.5

<sup>1.</sup> Emulated with external resistors.

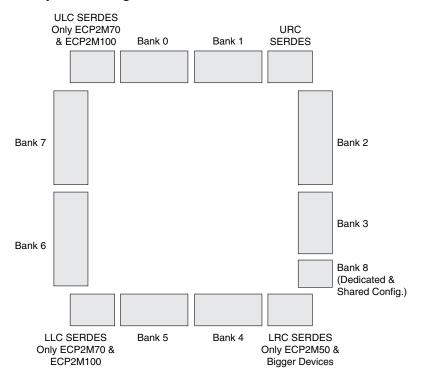
### sysIO Banking Scheme

LatticeECP2/M devices have eight general purpose programmable sysIO banks and a ninth configuration bank. Each of the eight general purpose sysIO banks has a  $V_{CCIO}$  supply voltage, and two reference voltages,  $V_{REF1}$  and  $V_{REF2}$ . Figure 9-1 shows the eight general purpose banks and the configuration bank with associated supplies. Bank 8 is a bank dedicated to configuration logic and has seven dedicated configuration I/Os and 14 multiplexed configuration I/Os. Bank 8 does have the power supply pads ( $V_{CCIO}$  and  $V_{CCAUX}$ ) but does not have any independent  $V_{REF}$  pads. The I/Os in Bank 8 are connected to  $V_{REF}$  from Bank 3.

On the top and bottom banks, the sysIO buffer pair consists of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The left and right sysIO buffer pair consists of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input. In 50% of the pairs there is also one differential output driver. The two pads in the pair are described as "true" and "comp", where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.



Figure 9-1. LatticeECP2M sysIO Banking



Note: URC = upper right corner, LRC = lower right corner, ULC = upper left corner and LLC = lower left corner.

### V<sub>CCIO</sub> (1.2V/1.5V/1.8V/2.5V/3.3V)

There are a total of eight  $V_{CCIO}$  supplies,  $V_{CCIO0}$  -  $V_{CCIO7}$ . Each bank has a separate  $V_{CCIO}$  supply that powers the single-ended output drivers and the ratioed input buffers such as LVTTL, LVCMOS, and PCI. LVTTL, LVCMOS3.3, LVCMOS2.5 and LVCMOS1.2 also have fixed threshold options allowing them to be placed in any bank. The  $V_{CCIO}$  voltage applied to the bank determines the ratioed input standards that can be supported in that bank. It is also used to power the differential output drivers. In addition,  $V_{CCIO8}$  is used to supply power to the sysCONFIG<sup>TM</sup> signals.

### $V_{CCAUX}$ (3.3V)

In addition to the bank  $V_{CCIO}$  supplies, devices have a  $V_{CC}$  core logic power supply and a  $V_{CCAUX}$  auxiliary supply that powers the differential and referenced input buffers.  $V_{CCAUX}$  is used to supply I/O reference voltage requiring 3.3V to satisfy the common-mode range of the drivers and input buffers.

### V<sub>CCJ</sub> (1.2V/1.5V/1.8V/2.5V/3.3V)

The JTAG pins have a separate  $V_{CCJ}$  power supply that is independent of the bank  $V_{CCIO}$  supplies.  $V_{CCJ}$  determines the electrical characteristics of the LVCMOS JTAG pins, both the output high level and the input threshold.

Table 9-3 shows a summary of all the required power supplies.



Table 9-3. Power Supplies

Power Supply	Description	Value <sup>1</sup>
V <sub>CC</sub>	Core Power Supply	1.2V
V <sub>CCIO</sub>	Power Supply for the I/O and Configuration Banks	1.2V/1.5V/1.8V/2.5V/3.3V
V <sub>CCAUX</sub>	Auxiliary Power Supply	3.3V
V <sub>CCJ</sub>	Power Supply for JTAG Pins	1.2V/1.5V/1.8V/2.5V/3.3V

<sup>1.</sup> Refer to LatticeECP2/M Family Data Sheet for recommended min. and max. values.

### Input Reference Voltage (V<sub>REF1.</sub> V<sub>REF2</sub>)

Each bank can support up to two separate  $V_{REF}$  input voltages,  $V_{REF1}$  and  $V_{REF2}$ , that are used to set the threshold for the referenced input buffers. The locations of these  $V_{REF}$  pins are pre-determined within the bank. These pins can be used as regular I/Os if the bank does not require a  $V_{REF}$  voltage.

### V<sub>REF1</sub> for DDR Memory Interface

When interfacing to DDR memory, the  $V_{REF1}$  input must be used as the reference voltage for the DQS and DQ input from the memory. A voltage divider between  $V_{REF1}$  and GND is used to generate an on-chip reference voltage that is used by the DQS transition detector circuit. This voltage divider is only present on  $V_{REF1}$  it is not available on  $V_{REF2}$ . For more information on the DQS transition detect logic and its implementation, please refer to TN1105, LatticeECP2/M High-Speed I/O Interface. DDR1 follows the SSTL25\_II signaling specification and DDR2 follows the SSTL18\_II signaling specification.

### Mixed Voltage Support in a Bank

The LatticeECP2/M sysIO buffer is connected to three parallel ratioed input buffers. These three parallel buffers are connected to  $V_{CCIO}$ ,  $V_{CCAUX}$  and  $V_{CC}$ , giving support for thresholds that track with  $V_{CCIO}$  as well as fixed thresholds for 3.3V ( $V_{CCAUX}$ ) and 1.2V ( $V_{CC}$ ) inputs. This allows the input threshold for ratioed buffers to be assigned on a pin-by-pin basis rather than tracking with  $V_{CCIO}$ . This option is available for all 1.2V, 2.5V and 3.3V ratioed inputs and is independent of the bank  $V_{CCIO}$  voltage. For example, if the bank  $V_{CCIO}$  is 1.8V, it is possible to have 1.2V and 3.3V ratioed input buffers with fixed thresholds, as well as 2.5V ratioed inputs with tracking thresholds.

Prior to device configuration, the ratioed input thresholds always tracks the bank  $V_{CCIO}$ . This option only takes effect after configuration. Output standards within a bank are always set by  $V_{CCIO}$ . Table 9-4 shows the sysIO standards that can be mixed in the same bank.

Table 9-4. Mixed Voltage Support

	Input sysIO Standards				Output	t sysIO Sta	ndards			
$v_{ccio}$	1.2V	1.5V	1.8V	2.5V	3.3V	1.2V	1.5V	1.8V	2.5V	3.3V
1.2V	Yes			Yes	Yes	Yes				
1.5V	Yes	Yes		Yes	Yes		Yes			
1.8V	Yes		Yes	Yes	Yes			Yes		
2.5V	Yes			Yes	Yes				Yes	
3.3V	Yes			Yes	Yes					Yes



### sysIO Standards Supported by Bank

Table 9-5. I/O Standards Supported by Bank

Description	Top Side	Right Side	Bottom Side	Left Side
	Banks 0-1	Banks 2-3	Banks 4-5	Banks 6-7
I/O Buffers	Single-ended	Single-ended and Differential	Single-ended	Single-ended and Differential
Output Standards Supported	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12
	SSTL18 Class I, II	SSTL18 Class I, II	SSTL18 Class I, II	SSTL18 Class I, II
	SSTL25 Class I, II	SSTL25 Class I, II	SSTL2 Class I, II	SSTL2 Class I, II
	SSTL33 Class I, II	SSTL33 Class I, II	SSTL3 Class I, II	SSTL3 Class I, II
	HSTL15 Class I	HSTL15 Class I	HSTL15 Class I	HSTL15 Class I, III
	HSTL18_I, II	HSTL18 Class I, II	HSTL18 Class I, II	HSTL18 Class I, II, III
	SSTL18D Class I, II	SSTL18D Class I, II	SSTL18D Class I, II	SSTL18D Class I, II
	SSTL25D Class I, II	SSTL25D Class I, II	SSTL25D Class I, II,	SSTL25D Class I, II,
	SSTL33D Class I, II	SSTL33D Class I, II	SSTL33D Class I, II	SSTL33D_I, II
	HSTL15D Class I	HSTL15D Class I	HSTL15D Class I	HSTL15D Class I
	HSTL18D Class I, II	HSTL18D Class I, II	HSTL18D Class I, II	HSTL18D Class I, II
	LVDS25E <sup>1</sup> LVPECL <sup>1</sup> BLVDS <sup>1</sup> RSDS <sup>1</sup>	LVDS LVDS25E <sup>1</sup> LVPECL <sup>1</sup> BLVDS <sup>1</sup> RSDS <sup>1</sup>	PCI33 LVDS25E <sup>1</sup> LVPECL <sup>1</sup> BLVDS <sup>1</sup> RSDS <sup>1</sup>	LVDS LVDS25E <sup>1</sup> LVPECL <sup>1</sup> BLVDS <sup>1</sup> RSDS <sup>1</sup>
Inputs	All Single-ended,	All Single-ended,	All Single-ended,	All Single-ended,
	Differential	Differential	Differential	Differential
Clock Inputs	All Single-ended,	All Single-ended,	All Single-ended,	All Single-ended,
	Differential	Differential	Differential	Differential
PCI Support	PCI33 without clamp	PCI33 without clamp	PCI33 with clamp	PCI33 without clamp PCI33 with clamp (ECP2M)
LVDS Output Buffers		LVDS (3.5mA) Buffers <sup>2</sup>		LVDS (3.5mA) Buffers <sup>2</sup>

<sup>1.</sup> These differential standards are implemented by using a complementary LVCMOS driver with external resistor pack.

# sysIO Buffer Configurations

All LVCMOS buffer have programmable pull, programmable drive and programmable slew configurations that can be set in the software.

#### **Bus Maintenance Circuit**

Each pad has a weak pull-up, weak pull-down and weak buskeeper capability. The pull-up and pull-down settings offer a fixed characteristic, which is useful in creating wired logic such as wired ORs. However, current can be slightly higher than other options, depending on the signal state. The bus-keeper option latches the signal in the last driven state, holding it at a valid level with minimal power dissipation. Users can also choose to turn off the bus maintenance circuitry, minimizing power dissipation and input leakage. Note that in this case, it is important to ensure that inputs are driven to a known state to avoid unnecessary power dissipation in the input buffer.

<sup>2.</sup> Available only on 50% of the I/Os in the bank.



### **Programmable Drive**

Each LVCMOS or LVTTL, as well as some of the referenced (SSTL and HSTL) output buffers, has a programmable drive strength option. This option can be set for each I/O independently. The drive strength settings available are 2mA, 4mA, 6mA, 8mA, 12mA, 16mA and 20mA. Actual options available vary by the I/O voltage. The user must consider the maximum allowable current per bank and the package thermal limit current when selecting the drive strength. Table 9-6 shows the available drive settings for each out the output standards.

Table 9-6. Programmable Drive Values for Single-ended Buffers

Single Ended I/O Standards	Programmable Drive (mA)
HSTL15_I/ HSTL15D_I	4, 8
HSTL18_I/ HSTL18D_I	8, 12
SSTL25_I/ SSTL25D_I	8, 12
SSTL25_II/ SSTL25D_II	16, 20
SSTL18_II/SSTL18D_II	8, 12
LVCMOS12	2, 6
LVCMOS15	4, 8
LVCMOS18	4, 8, 12, 16
LVCMOS25	4, 8, 12, 16, 20
LVCMOS33	4, 8, 12, 16, 20
LVTTL	4, 8, 12, 16, 20

### **Programmable Slew Rate**

Each LVCMOS or LVTTL output buffer pin also has a programmable output slew rate control that can be configured for either low noise or high-speed performance. Each I/O pin has an individual slew rate control. This allows designers to specify slew rate control on a pin-by-pin basis. This slew rate control affects both the rising and falling edges.

### **Open-Drain Control**

All LVCMOS and LVTTL output buffers can be configured to function as open drain outputs. The user can implement an open drain output by turning on the OPENDRAIN attribute in the software.

### **Differential SSTL and HSTL Support**

The single-ended driver associated with the complementary 'C' pad can optionally be driven by the complement of the data that drives the single-ended driver associated with the true pad. This allows a pair of single-ended drivers to be used to drive complementary outputs with the lowest possible skew between the signals. This is used for driving complementary SSTL and HSTL signals (as required by the differential SSTL and HSTL clock inputs on synchronous DRAM and synchronous SRAM devices respectively). This capability is also used in conjunction with off-chip resistors to emulate LVPECL, and BLVDS output drivers.

### **PCI Support with Programmable PCICLAMP**

Each sysIO buffer can be configured to support PCI33. The buffers on the bottom of the device (for LatticeECP2) or on the left and bottom sides of the device (for LatticeECP2M) have an optional PCI clamp diode that may optionally be specified in the ispLEVER design tools.

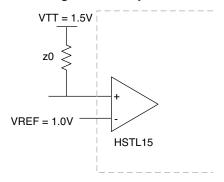
Programmable PCICLAMP can be turned ON or OFF. This option is available on each I/O independently on the bottom side banks (for LatticeECP2) or on the left and bottom side banks (for LatticeECP2M).



### **GTL+ Input Support**

GTL+ inputs are supported using the HSTL15\_I input standard with VREF set to 1.0V and external VTT termination set to 1.5V. GTL+ inputs implemented using this method can support the maximum speed listed for the HSTL standard in the <a href="LatticeECP2/M Family Data Sheet">LatticeECP2/M Family Data Sheet</a> . GTL+ outputs are not supported in the LatticeECP2 device.

Figure 9-2. GTL+ Input Buffer Emulation Using HSTL15 Input



### **Programmable Input Delay**

Each input can optionally be delayed before it is passed to the core logic or input registers. The primary use for the input delay is to achieve zero hold time for the input registers when using a direct drive primary clock. To arrive at zero hold time, the input delay will delay the data by at least as much as the primary clock injection delay. This option can be turned ON or OFF for each I/O independently in the software using the FIXEDDELAY attribute. This attribute is described in more detail in the software sysIO attribute section. Appendix A shows how this feature can be enabled in the software using HDL attributes.

### **Software sysIO Attributes**

sysIO attributes can be specified in the HDL, using the Preference Editor GUI or in the ASCII preference file (.prf) file directly. Appendices A, B and C list examples of how these can be assigned using each of these methods. This section describes each of these attributes in detail.

#### **IO TYPE**

This is used to set the sysIO standard for an I/O. The  $V_{CCIO}$  required to set these I/O standards are embedded in the attribute names itself. There is no separate attribute to set the  $V_{CCIO}$  requirements. Table 9-7 lists the available I/O types.



### Table 9-7. IO\_TYPE Attribute Values

syslO Signaling Standard	IO_TYPE
DEFAULT	LVCMOS25
LVDS 2.5V	LVDS25
RSDS	RSDS
Emulated LVDS 2.5V	LVDS25E <sup>1</sup>
Bus LVDS 2.5V	BLVDS25 <sup>1</sup>
LVPECL 3.3V	LVPECL33 <sup>1</sup>
HSTL18 Class I and II	HSTL18_I, HTSL18_II
Differential HSTL 18 Class I and II	HSTL18D_I, HSTL18D_II
HSTL 15 Class I	HSTL15_I
Differential HSTL 15 Class I	HSTL15D_I
SSTL 33 Class I and II	SSTL33_I, SSTL33_II
Differential SSTL 33 Class I and II	SSTL33D_I, SSTL3D_II
SSTL 25 Class I and II	SSTL25_I,SSTL25_II
Differential SSTL 25 Class I and II	SSTL25D_I, SSTL25D_II
SSTL 18 Class I and II	SSTL18_I, SSTL18_II
Differential SSTL 18 Class I	SSTL18D_I,SSTL18D_II
LVTTL	LVTTL33
3.3V LVCMOS	LVCMOS33
2.5V LVCMOS	LVCMOS25
1.8V LVCMOS	LVCMOS18
1.5V LVCMOS	LVCMOS15
1.2V LVCMOS	LVCMOS12
3.3V PCI	PCI33

These differential standards are implemented by using a complementary LVCMOS driver with external resistor pack.

#### **OPENDRAIN**

LVCMOS and LVTTL I/O standards can be set to open drain configuration by using the OPENDRAIN attribute.

Values: ON, OFF Default: OFF

#### **DRIVE**

The DRIVE attribute will set the programmable drive strength for the output standards that have programmable drive capability



Table 9-8. DRIVE Settings

Output Standard	DRIVE (mA)	Default (mA)
HSTL15_I/ HSTL15D_I	4, 8	8
HSTL18_I/ HSTL18D_I	8, 12	12
SSTL25_I/ SSTL25D_I	8, 12	8
SSTL25_II/ SSTL25D_II	16, 20	16
SSTL18_II/SSTL18D_II	8, 12	12
LVCMOS12	2, 6	6
LVCMOS15	4, 8	8
LVCMOS18	4, 8, 12, 16	12
LVCMOS25	4, 8, 12, 16, 20	12
LVCMOS33	4, 8, 12, 16, 20	12
LVTTL	4, 8, 12, 16, 20	12

#### **PULLMODE**

The PULLMODE attribute is available for all the LVTLL and LVCMOS inputs and outputs. This attribute can be enabled for each I/O independently.

Values: UP, DOWN, NONE, KEEPER

Default: UP

Table 9-9. PULLMODE Values

PULL Options	PULLMODE Value
Pull-up (Default)	UP
Pull-down	DOWN
Bus Keeper	KEEPER
Pull Off	NONE

#### **PCICLAMP**

PCI33 inputs on the bottom of the device (for LatticeECP2) or on the left and bottom sides of the device (for LatticeECP2M) have an optional PCI clamp that is enabled via the PCICLAMP attribute. The PCICLAMP is also available for all LVCMOS33 and LVTTL inputs.

Values: ON, OFF Default: OFF

Table 9-10. PCICLAMP Values

Input Type	PCICLAMP Value
PCI33	ON
LVCMOS33	OFF (default), ON
LVTTL	OFF (default), ON

#### SLEWRATE

The SLEWRATE attribute is available for all LVTTL and LVCMOS output drivers. Each I/O pin has an individual slew rate control. This allows a designer to specify slew rate control on a pin-by-pin basis.

Values: FAST, SLOW

Default: FAST



#### **FIXEDDELAY**

The FIXEDDELAY attribute is available to each input pin. This attribute, when enabled, is used to achieve zero hold time for the input registers when using global clock. This attribute can only be assigned in the HDL source.

Values: TRUE, FALSE

Default: FALSE

#### **INBUF**

By default, all the unused input buffers are disabled. The INBUF attribute is used to enable the unused input buffers when performing a boundary scan test. This is a global attribute and can be globally set to ON or OFF.

Values: ON, OFF Default: OFF

#### DIN/DOUT

This attribute can be used to assign I/O registers. Using DIN will assert an input register and using the DOUT attribute will assert an output register. By default, the software will try to assign the I/O registers, if applicable. The user can turn this OFF by using the synthesis attribute or by using the Preference Editor of the ispLEVER software. These attributes can only be applied to registers.

#### LOC

This attribute can be used to make pin assignments to the I/O ports in the design. This attributes is only used when the pin assignments are made in HDL source. Designers can also assign pins directly using the GUI in the Preference Editor of the ispLEVER software. The appendices explain this in further detail.

### **Design Considerations and Usage**

This section discusses some of the design rules and considerations that must be taken into account when designing with the LatticeECP2/M sysIO buffer

### **Banking Rules**

- If V<sub>CCIO</sub> or V<sub>CCJ</sub> for any bank is set to 3.3 V, it is recommended that it be connected to the same power supply as V<sub>CCAUX</sub>, thus minimizing leakage.
- If V<sub>CCIO</sub> or V<sub>CCJ</sub> for any bank is set to 1.2V, it is recommended that it be connected to the same power supply as V<sub>CC</sub>, thus minimizing leakage.
- When implementing DDR memory interfaces, the V<sub>REF1</sub> of the bank is used to provide reference to the interface pins and cannot be used to power any other referenced inputs.
- Only the bottom banks for LatticeECP2 (Banks 4 and 5) or left and bottom banks for LatticeECP2M (Banks 4, 5, 6 and 7) will support PCI clamps.
- All legal input buffers should be independent of bank V<sub>CCIO</sub>, except for 1.8V and 1.5V buffers, which require a bank V<sub>CCIO</sub> of 1.8V and 1.5V.

### **Differential I/O Rules**

- All banks can support LVDS input buffers. Only the banks on the right and left sides (Banks 2, 3, 6 and 7) will
  support True Differential output buffers. The banks on the top and bottom will support the LVDS input buffers but
  will not support True LVDS outputs. The user can use emulated LVDS output buffers on these banks.
- All banks support emulated differential buffers using external resistor pack and complementary LVCMOS drivers.
- Only 50% of the I/Os on the left and right sides can provide LVDS output buffer capability. LVDS can only be assigned to the TRUE pad. The ispLEVER design tool will automatically assign the other I/Os of the differential pair to the complementary pad. Refer to the device data sheet to see the pin listings for all LVDS pairs.



### Assigning V<sub>REF1</sub>/ V<sub>REF2</sub> Groups for Referenced Inputs

Each bank has two dedicated  $V_{REF}$  input pins,  $V_{REF1}$  and  $V_{REF2}$ . Designers can group buffers to a particular  $V_{REF1}$  rail,  $V_{REF1}$  or  $V_{REF2}$ . This grouping is done by assigning a PGROUP VREF preference along with the LOCATE PGROUP preference.

#### **Preference Syntax**

```
PGROUP <pgrp_name> [(VREF <vref_name>)+] (COMP <comp_name>)+;
LOCATE PGROUP <pgrp_name> BANK <bank_num>;
LOCATE VREF <vref_name> SITE <site_name>;
```

#### **Example Showing VREF Groups**

```
PGROUP "vref_pg1" VREF "ref1" COMP "ah(0)" COMP "ah(1)" COMP "ah(2)" COMP "ah(3)" COMP "ah(4)" COMP "ah(5)" COMP "ah(6)" COMP "ah(7)";

PGROUP "vref_pg2" VREF "ref2" COMP "al(0)" COMP "al(1)" COMP "al(2)" COMP "al(3)" COMP "al(4)" COMP "al(5)" COMP "al(6)" COMP "al(7)";

LOCATE VREF "ref1" SITE PR29C;
LOCATE VREF "ref2" SITE PR48B;

Or

LOCATE PGROUP " vref_pg1" BANK 2;
LOCATE PGROUP " vref_pg2" BANK 2;
```

The example shows two  $V_{REF}$  groups, "vref\_pg1" assigned to VREF "ref1" and "vref\_pg2" assigned to "ref2". The user must lock these  $V_{REF}$  to either  $V_{REF1}$  or  $V_{REF2}$  using the LOCATE preference. Alternatively, users can designate to which bank the  $V_{REF}$  group should be located. The software will then assign these to either the  $V_{REF1}$  or  $V_{REF2}$  of the bank.

If the PGROUP VREF is not used, the software will automatically group all pins that need the same  $V_{REF}$  reference voltage. This preference is most useful when there is more than one bus that uses the same reference voltage and the user wishes to associate each of these busses to different  $V_{REF}$  resources.

# **Differential I/O Implementation**

The LatticeECP2/M devices support a variety of differential standards as detailed in the following sections.

#### LVDS

True LVDS (LVDS25) drivers are available on 50% of the I/Os on the left and right side of the devices. LVDS input support is provided on all sides of the device. All four sides of the device support LVDS using complementary LVC-MOS drivers with external resistors (LVDS25E). Refer to the <a href="LatticeECP2/M Family Data Sheet">LatticeECP2/M Family Data Sheet</a> for a detailed explanation of these LVDS implementations.

#### **BLVDS**

All single-ended sysIO buffers pairs support the Bus-LVDS standard using complementary LVCMOS drivers with external resistors. Please refer to the <u>LatticeECP2/M Family Data Sheet</u> for a detailed explanation of BLVDS implementation.

#### **RSDS**

All single-ended sysIO buffers pairs support RSDS standard using complementary LVCMOS drivers with external resistors. Please refer to the <u>LatticeECP2/M Family Data Sheet</u> for a detailed explanation of RSDS implementation.



#### **LVPECL**

All the sysIO buffers will support LVPECL inputs. LVPECL outputs are supported using complementary LVCMOS driver with external resistors. Please refer to the <u>LatticeECP2/M Family Data Sheet</u> for a detailed explanation of LVPECL implementation.

#### **Differential SSTL and HSTL**

All single-ended sysIO buffers pairs support differential SSTL and HSTL. Please refer to the <u>LatticeECP2/M Family Data Sheet</u> for a detailed explanation of Differential HSTL and SSTL implementation.

### **Technical Support Assistance**

e-mail: techsupport@latticesemi.com

Internet: www.latticesemi.com

### **Revision History**

Date	Version	Change Summary
February 2006	01.0	Initial release.
September 2006	01.1	Updated to include LatticeECP2M support.
April 2007	01.2	Updated Supported Output Standards table.
June 2007	01.3	Updated V <sub>REF1</sub> for DDR Memory Interface section.
June 2007	01.4	Updated sysIO Standards Supported by Bank table.
		Updated Banking Rules bullet list.
June 2007	01.5	Updated Power Supplies table.
April 2008	01.6	Updated LatticeECP2M sysIO Banking diagram.
February 2009	01.7	Updated I/O Standards Supported by Bank table.
June 2010	01.8	Updated screen shots in Appendix B.
		Updated document for Lattice Diamond design software support.
March 2011	01.9	Added support for GTL+ input standard using HSTL input buffer.
June 2013	02.0	Updated document with new corporate logo.
		Updated Technical Support Assistance information.



# Appendix A. HDL Attributes for Synplicity® and Precision® RTL Synthesis

Using these HDL attributes, designers can assign the sysIO attributes directly in their source. The attribute definition and syntax for the appropriate synthesis vendor must be used. Below are a list of all the sysIO attributes, syntax and examples for Precision RTL Synthesis and Synplicity. This section only lists the sysIO buffer attributes for these devices. You can refer to the Precision RTL Synthesis and Synplicity user manuals for a complete list of synthesis attributes. These manuals are available through the ispLEVER software Help system.

### VHDL Synplicity/Precision RTL Synthesis

This section lists syntax and examples for all the sysIO Attributes in VHDL when using the Precision RTL Synthesis or Synplicity synthesis tools.

#### **Syntax**

Table 9-11. VHDL Attribute Syntax for Synplicity and Precision RTL Synthesis

Attribute	Syntax
IO_TYPE	attribute IO_TYPE: string; attribute IO_TYPE of <i>Pinname</i> : signal is "IO_TYPE Value";
OPENDRAIN	attribute OPENDRAIN: string; attribute OPENDRAIN of <i>Pinname:</i> signal is "OpenDrain Value";
DRIVE	attribute DRIVE: string; attribute DRIVE of <i>Pinname</i> : signal is "Drive Value";
PULLMODE	attribute PULLMODE: string; attribute PULLMODE of <i>Pinname:</i> signal is "Pullmode Value";
PCICLAMP	attribute PCICLAMP: string; attribute PCICLAMP of <i>Pinname:</i> signal is "PCIClamp Value";
SLEWRATE	attribute PULLMODE: string; attribute PULLMODE of <i>Pinname:</i> signal is "Slewrate Value";
FIXEDDELAY	attribute FIXEDDELAY: string; attribute FIXEDDELAY of <i>Pinname:</i> signal is " <i>Fixeddelay Value</i> ";
DIN	attribute DIN: string; attribute DIN of <i>Pinname</i> : signal is "";
DOUT	attribute DOUT: string; attribute DOUT of <i>Pinname:</i> signal is "";
LOC	attribute LOC: string; attribute LOC of <i>Pinname</i> : signal is "pin_locations";

#### **Examples**

#### **IO TYPE**

```
--***Attribute Declaration***
ATTRIBUTE IO_TYPE: string;
--***IO_TYPE assignment for I/O Pin***
ATTRIBUTE IO_TYPE OF portA: SIGNAL IS "PCI33";
ATTRIBUTE IO_TYPE OF portB: SIGNAL IS "LVCMOS33";
ATTRIBUTE IO_TYPE OF portC: SIGNAL IS "LVCMOS33";
OPENDRAIN

--***Attribute Declaration***
ATTRIBUTE OPENDRAIN: string;
--***DRIVE assignment for I/O Pin***
ATTRIBUTE OPENDRAIN OF portB: SIGNAL IS "ON";
```



#### **DRIVE**

```
--***Attribute Declaration***
  ATTRIBUTE DRIVE: string;
   --***DRIVE assignment for I/O Pin***
   ATTRIBUTE DRIVE OF portB: SIGNAL IS "20";
PULLMODE
   --***Attribute Declaration***
   ATTRIBUTE PULLMODE : string;
   --***PULLMODE assignment for I/O Pin***
  ATTRIBUTE PULLMODE OF portA: SIGNAL IS "DOWN";
   ATTRIBUTE PULLMODE OF portB: SIGNAL IS "UP";
PCICLAMP
   --***Attribute Declaration***
   ATTRIBUTE PCICLAMP: string;
   --***PULLMODE assignment for I/O Pin***
   ATTRIBUTE PCICLAMP OF portA:
                                  SIGNAL IS "ON";
SLEWRATE
   --***Attribute Declaration***
   ATTRIBUTE SLEWRATE : string;
   --*** SLEWRATE assignment for I/O Pin***
   ATTRIBUTE SLEWRATE OF portB: SIGNAL IS "FAST";
FIXEDDELAY
   --***Attribute Declaration***
  ATTRIBUTE FIXEDDELAY: string;
   --*** SLEWRATE assignment for I/O Pin***
   ATTRIBUTE FIXEDDELAY OF portB: SIGNAL IS "TRUE";
DIN/DOUT
   --***Attribute Declaration***
  ATTRIBUTE din : string;
   ATTRIBUTE dout : string;
   --*** din/dout assignment for I/O Pin***
  ATTRIBUTE din OF input_vector: SIGNAL IS " ";
  ATTRIBUTE dout OF output_vector: SIGNAL IS " ";
LOC
   --***Attribute Declaration***
  ATTRIBUTE LOC : string;
   --*** LOC assignment for I/O Pin***
   ATTRIBUTE LOC OF input_vector: SIGNAL IS "E3,B3,C3 ";
```



### **Verilog Synplicity**

This section lists syntax and examples for all the sysIO Attributes in Verilog using the Synplicity synthesis tool.

#### **Syntax**

Table 9-12. Verilog Synplicity Attribute Syntax

Attribute	Syntax
IO_TYPE	PinType PinName /* synthesis IO_TYPE="IO_Type Value"*/;
OPENDRAIN	PinType PinName /* synthesis OPENDRAIN ="OpenDrain Value"*/;
DRIVE	PinType PinName /* synthesis DRIVE="Drive Value"*/;
PULLMODE	PinType PinName /* synthesis PULLMODE="Pullmode Value"*/;
PCICLAMP	PinType PinName /* synthesis PCICLAMP =" PCIClamp Value"*/;
SLEWRATE	PinType PinName /* synthesis SLEWRATE="Slewrate Value"*/;
FIXEDDELAY	PinType PinName /* synthesis FIXEDDELAY="Fixeddelay Value"*/;
DIN	PinType PinName /* synthesis DIN=" "*/;
DOUT	PinType PinName /* synthesis DOUT=" "*/;
LOC	PinType PinName /* synthesis LOC="pin_locations "*/;

#### **Examples**

```
//IO TYPE, PULLMODE, SLEWRATE and DRIVE assignment
output portB /*synthesis IO TYPE="LVCMOS33" PULLMODE ="UP" SLEWRATE ="FAST"
DRIVE ="20"*/;
output portC /*synthesis IO TYPE="LVDS25" */;
//OPENDRAIN
output portA /*synthesis OPENDRAIN ="ON"*/;
//PCICLAMP
output portA /*synthesis IO TYPE="PCI33" PULLMODE ="PCICLAMP"*/;
// Fixeddelay
input load /* synthesis FIXEDDELAY="TRUE" */;
// Place the flip-flops near the load input
input load /* synthesis din="" */;
// Place the flip-flops near the outload output
output outload /* synthesis dout="" */;
//I/O pin location
input [3:0] DATA0 /* synthesis loc="E3,B1,F3"*/;
//Register pin location
reg data in ch1 buf reg3 /* synthesis loc="R40C47" */;
//Vectored internal bus
reg [3:0] data in ch1 reg /*synthesis loc ="R40C47,R40C46,R40C45,R40C44" */;
```



### **Verilog Precision**

This section lists syntax and examples for all the sysIO Attributes in Verilog using the Precision RTL Synthesis tool.

#### **Syntax**

Table 9-13. Verilog Precision Attribute Syntax

Attribute	Syntax
IO_TYPE	//pragma attribute PinName IO_TYPE IO_TYPE Value
OPENDRAIN	// pragma attribute PinName OPENDRAIN OpenDrain Value
DRIVE	// pragma attribute <i>PinName</i> DRIVE Drive Value
PULLMODE	// pragma attribute PinName IO_TYPE Pullmode Value
PCICLAMP	// pragma attribute PinName PCICLAMP PCIClamp Value
SLEWRATE	// pragma attribute PinName IO_TYPE Slewrate Value
FIXEDDELAY	// pragma attribute PinName IO_TYPE Fixeddelay Value
LOC	// pragma attribute PinName LOC pin_location

#### **Examples**

```
//****IO TYPE ***
//pragma attribute portA IO_TYPE PCI33
//pragma attribute portB IO_TYPE LVCMOS33
//pragma attribute portC IO_TYPE SSTL25_II
//*** Opendrain ***
//pragma attribute portB OPENDRAIN ON
//pragma attribute portD OPENDRAIN OFF
//*** Drive ***
//pragma attribute portB DRIVE 20
//pragma attribute portD DRIVE 8
//*** Pullmode***
//pragma attribute portB PULLMODE UP
//*** PCIClamp***
//pragma attribute portB PCICLAMP ON
//*** Slewrate ***
//pragma attribute portB SLEWRATE FAST
//pragma attribute portD SLEWRATE SLOW
// ***Fixeddelay***
// pragma attribute load FIXEDDELAY TRUE
//***LOC***
//pragma attribute portB loc E3
```



# Appendix B. sysIO Attributes Using the ispLEVER Design Planner User Interface

Designers can assign sysIO buffer attributes using the Design Planner Spreadsheet View GUI available in the isp-LEVER design tool. If you are using Lattice Diamond™ design software, refer to Appendix D. The Pin Attribute Sheet list all the ports in a design and all the available sysIO attributes as preferences. By clicking on each of these cells, a list of all the valid I/O preference for that port is displayed. Each column takes precedence over the next. Therefore, when a particular IO\_TYPE is chosen, the DRIVE, PULLMODE and SLEWRATE columns will only list the valid combinations for that IO\_TYPE. The pin locations can be locked using the pin location column of the Pin Attribute sheet. Right-clicking on a cell will list the available pin locations. The Preference Editor will also conduct a DRC check to search for any incorrect pin assignments.

Designers can enter DIN/DOUT preferences using the Cell Attributes sheet of the Preference Editor. All the preferences assigned using the Preference Editor are written into the preference file (.prf).

Figures 2 and 3 show the Pin Attribute sheet and the Cell Attribute sheet views of the preference editor. For further information on how to use the Preference Editor, refer to the ispLEVER Help documentation in the Help menu option of the software.

Figure 9-3. Pin Attributes Tab

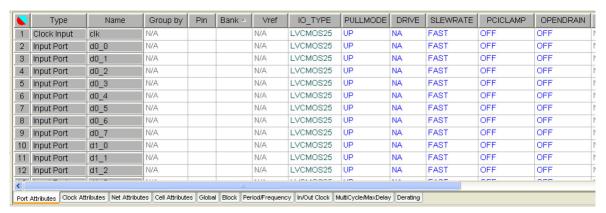


Figure 9-4. Cell Attributes Tab





# Appendix C. sysIO Attributes Using Preference File (ASCII File)

Designers can enter sysIO attributes directly in the preference (.prf) file as sysIO buffer preferences. The PRF file is an ASCII file containing two separate sections: a schematic section for those preferences created by the mapper or translator, and a user section for preferences entered by the user. User preferences can be written directly into this file. The synthesis attributes appear between the schematic start and schematic end of the file. The sysIO buffer preferences can be entered after the schematic end line using the preference file syntax. Below are a list of sysIO buffer preference syntax and examples.

#### **IOBUF**

This preference is used to assign the attribute IO\_TYPE, PULLMODE, SLEWRATE and DRIVE.

#### **Syntax**

```
IOBUF [ALLPORTS | PORT <port_name> | GROUP <group_name>] (keyword=<value>)+;
where:
```

<port\_name> = These are not the actual top-level port names, but should be the signal name attached to the port. PIOs in the physical design (.ncd) file are named using this convention. Any multiple listings or wildcarding should be done using GROUPs

Keyword = IO\_TYPE, OPENDRAIN, DRIVE, PULLMODE, PCICLAMP, SLEWRATE.

#### Example

```
IOBUF PORT "port1" IO_TYPE=LVTTL33 OPENDRAIN=ON DRIVE=8 PULLMODE=UP
PCICLAMP =OFF SLEWRATE=FAST;
DEFINE GROUP "bank1" "in*" "out_[0-31]";
IOBUF GROUP "bank1" IO_TYPE=SSTL18_II;
```

#### **LOCATE**

When this preference is applied to a specified component, it places the component at a specified site and locks the component to the site. If applied to a specified macro instance, it places the macro's reference component at a specified site, places all of the macro's pre-placed components (that is, all components that were placed in the macro's library file) in sites relative to the reference component, and locks all of these placed components at their sites. This can also be applied to a specified PGROUP.

### **Syntax**

```
LOCATE [COMP <comp_name> | MACRO <macro_name>] SITE <site_name>;
LOCATE PGROUP <pgroup_name> [SITE <site_name>; | REGION <region_name>;]
LOCATE PGROUP <pgroup_name> RANGE <site_1> [<site_2> | <count>] [<direction>] |
RANGE <chip_side> [<direction>];
LOCATE BUS < bus_name> ROW|COL <number>;
<bus_name> := string
<number> := integer
```

Note: If the comp\_name, macro\_name, or site\_name begins with anything other than an alpha character (for example, "11C7"), you must enclose the name in quotes. Wildcard expressions are allowed in <comp\_name>.

#### **Examples**

This command places the port Clk0 on the site A4:

```
LOCATE COMP "Clk0" SITE "A4";
```



This command places the component PFU1 on the site named R1C7:

```
LOCATE COMP "PFU1" SITE "R1C7";
```

This command places bus1 on ROW 3 and bus2 on COL4

```
LOCATE BUS "bus1" ROW 3;
LOCATE BUS "bus2" COL 4;
```

#### **USE DIN CELL**

This preference specifies the given register to be used as an input flip-flop.

#### **Syntax**

#### **USE DOUT CELL**

Specifies the given register to be used as an output flip-flop.

#### **Syntax**

#### **PGROUP VREF**

This preference is used to group all the components that need to be associated to one V<sub>RFF</sub> pin within a bank.

#### Syntax 1 4 1

```
PGROUP <pgrp_name> [(VREF <vref_name>)+] (COMP <comp_name>)+;
LOCATE PGROUP <pgrp_name> BANK <bank_num>;
LOCATE VREF <vref_name> SITE <site_name>;
```

#### **Example**

```
PGROUP "vref_pg1" VREF "ref1" COMP "ah(0)" COMP "ah(1)" COMP "ah(2)" COMP "ah(3)" COMP "ah(4)" COMP "ah(5)" COMP "ah(6)" COMP "ah(7)";

PGROUP "vref_pg2" VREF "ref2" COMP "al(0)" COMP "al(1)" COMP "al(2)" COMP "al(3)" COMP "al(4)" COMP "al(5)" COMP "al(6)" COMP "al(7)";

LOCATE VREF "ref1" SITE PR29C;

LOCATE VREF "ref2" SITE PR48B;

Or:

LOCATE PGROUP " vref_pg1" BANK 2;

LOCATE PGROUP " vref_pg2" BANK 2;
```



### Appendix D. Assigning sysIO Attributes Using Lattice Diamond Spreadsheet View

sysIO buffer attributes can be assigned using the Spreadsheet View available in the Lattice Diamond design software. The Port Assignments Sheet lists all the ports in a design and all the available sysIO attributes in multiple columns. Click on each of these cells for a list of all the valid I/O preferences for that port. Each column takes precedence over the next. Therefore, when you choose a particular IO\_TYPE, the columns for the DRIVE, PULL-MODE, SLEWRATE and other attributes will only list the valid entries for that IO TYPE.

Pin locations can be locked using the Pin column of the Port Assignments sheet or using the Pin Assignments sheet. You can right-click on a cell and go to Assign Pins to see a list of available pins.

The Spreadsheet View also has an option to run a DRC check to check for any incorrect pin assignments. You can enter the DIN/ DOUT preferences using the Cell Mapping Tab. All the preferences assigned using the Spreadsheet View are written into the logical preference file (.lpf).

Figure 9-5 shows the Port Assignments Sheet of the Spreadsheet View. For further information on how to use the Spreadsheet View, refer to the Diamond Help documentation, available in the Help menu option of the software.

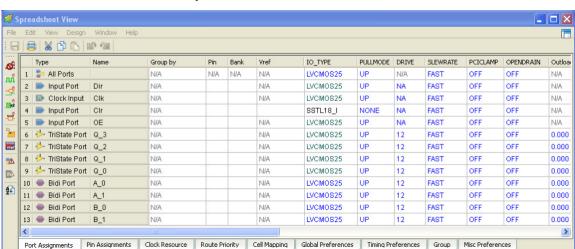


Figure 9-5. Port Attributes Tab of the SpreadSheet View

Users can create a VREF pin using the Spreadsheet View as shown in Figure 9-6 and then assign VREF for a bank using the VREF Column in the Ports Assignment Tab of the Spreadsheet View as shown in Figure 9-7. See the Diamond online help for a detailed description of this setting.



Figure 9-6. Creating a VREF in Spreadsheet View

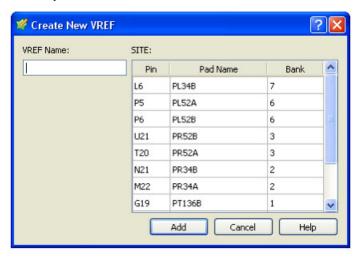


Figure 9-7. Assigning VREF for an Input Port in Spreadsheet View

